

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE (π -MOSVI)

2SK3129

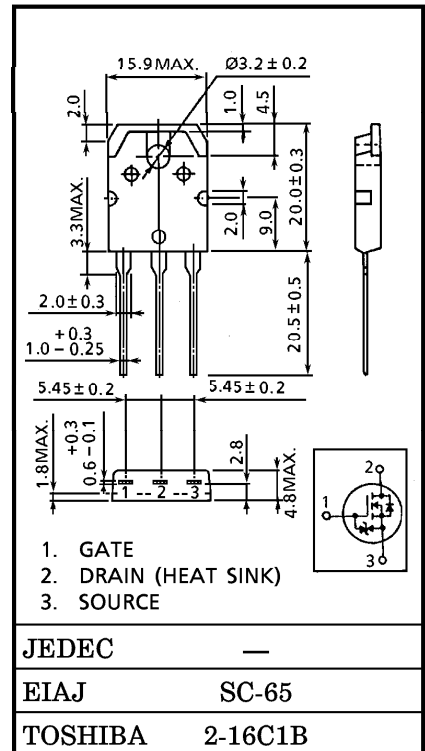
HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS
 CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE APPLICATIONS

INDUSTRIAL APPLICATIONS
 Unit in mm

- Low Drain-Source ON Resistance : $R_{DS(ON)} = 5.5 \text{ m}\Omega$ (Typ.)
- High Forward Transfer Admittance: $|Y_{fs}| = 70 \text{ S}$ (Typ.)
- Low Leakage Current : $I_{DSS} = 100 \mu\text{A}$ (Max.) ($V_{DS} = 30 \text{ V}$)
- Enhancement-Mode : $V_{th} = 0.8 \sim 2.0 \text{ V}$
 ($V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}$)

MAXIMUM RATINGS ($T_a = 25^\circ\text{C}$)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Drain-Source Voltage	V_{DSS}	50	V
Drain-Gate Voltage ($R_{GS} = 20 \text{ k}\Omega$)	V_{DGR}	50	V
Gate-Source Voltage	V_{GSS}	± 20	V
Drain Current	DC	I_D	60
	Pulse	I_{DP}	240
Drain Power Dissipation ($T_c = 25^\circ\text{C}$)	P_D	150	W
Single Pulse Avalanche Energy**	E_{AS}	721	mJ
Avalanche Current	I_{AR}	60	A
Repetitive Avalanche Energy*	E_{AR}	12	mJ
Channel Temperature	T_{ch}	150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	$-55 \sim 150$	$^\circ\text{C}$



THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	$R_{th(ch-c)}$	0.833	$^\circ\text{C/W}$
Thermal Resistance, Channel to Ambient	$R_{th(ch-a)}$	50	$^\circ\text{C/W}$

Note ;

- * Repetitive rating ; Pulse Width Limited by Max. junction temperature.
- ** $V_{DD} = 25 \text{ V}, T_{ch} = 25^\circ\text{C}$ (initial), $L = 246 \mu\text{H}, R_G = 25 \Omega, I_{AR} = 60 \text{ A}$

**This transistor is an electrostatic sensitive device.
 Please handle with caution.**

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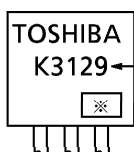
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage Current		IGSS	VGS = ±16 V, VDS = 0 V	—	—	±10	μA
Drain Cut-off Current		IDSS	VDS = 30 V, VGS = 0 V	—	—	100	μA
Drain-Source Breakdown Voltage		V(BR)DSS	ID = 10 mA, VGS = 0 V	50	—	—	V
Gate Threshold Voltage		Vth	VDS = 10 V, ID = 1 mA	0.8	—	2.0	V
Drain-Source ON Resistance		RDS(ON)	VGS = 10 V, ID = 30 A	—	5.5	7	mΩ
Forward Transfer Admittance		Yfs	VDS = 10 V, ID = 30 A	40	70	—	S
Input Capacitance		Ciss	VDS = 10 V, VGS = 0 V f = 1 MHz	—	3700	—	pF
Reverse Transfer Capacitance		Crss		—	650	—	
Output Capacitance		Coss		—	1800	—	
Switching Time	Rise Time	tr	<p> $V_{GS} = 10\text{ V}$ $V_{GS} = 0\text{ V}$ $I_D = 30\text{ A}$ $R_L = 0.83\ \Omega$ $V_{DD} \doteq 25\text{ V}$ $V_{IN} : t_r, t_f < 5\text{ ns}$ Duty $\leq 1\%$, $t_w = 10\ \mu\text{s}$ </p>	—	20	—	ns
	Turn-on Time	ton		—	35	—	
	Fall Time	tf		—	160	—	
	Turn-off Time	toff		—	480	—	
Total Gate Charge (Gate-Source Plus Gate-Drain)		Qg	VDD $\doteq 40\text{ V}$, VGS = 10 V ID = 60 A	—	135	—	nC
Gate-Source Charge		Qgs		—	90	—	
Gate-Drain (“Miller”) Charge		Qgd		—	45	—	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	IDR	—	—	—	60	A
Pulse Drain Reverse Current	IDRP	—	—	—	240	A
Diode Forward Voltage	VDSF	IDR = 60 A, VGS = 0 V	—	—	-1.4	V
Reverse Recovery Time	trr	IDR = 60 A, VGS = 0 V	—	180	—	ns
Reverse Recovery Charge	Qrr	dIDR / dt = 50 A / μs	—	0.32	—	μC

MARKING



TYPE

※ Lot Number

□ □ — Month (Starting from Alphabet A)

— Year (Last Number of the Christian Era)